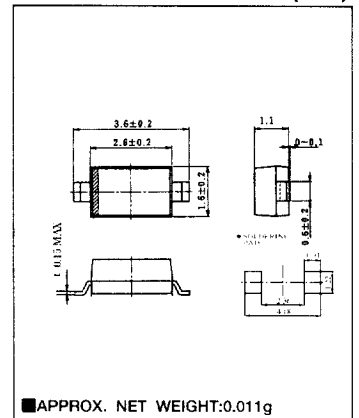


0.5A Avg. 100 Volts SBD EP05H10

■最大定格 MAXIMUM RATINGS

Rating	Symbol	Type	EP05H10	Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	V_{RRM}		100	V
平均整流電流 Average Rectified Output Current	I_O	Glass-Epoxy Substrate mounted *	0.48 (商用周波数、正弦波180度通電 $T_a=25^\circ\text{C}$) Half Sine Wave, Resistive Load	A
			0.50 (商用周波数、正弦波180度通電 $T_l=118^\circ\text{C}$) Half Sine Wave, Resistive Load (Tl: Lead Temperature)	A
実効順電流 RMS Forward Current	$I_{F(RMS)}$		0.785	A
サージ順電流 Surge Forward Current	I_{FSM}		8 (50Hz単相正弦波1サイクル非くり返し) Half Sine Wave, 1cycle, Non-repetitive	A
動作接合温度範囲 Operating Junction Temperature Range	T_{jw}		-40~+150	$^\circ\text{C}$
保存温度範囲 Storage Temperature Range	T_{stg}		-40~+150	$^\circ\text{C}$

■OUTLINE DRAWING(mm)



■電気的特性 ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	I_{RM}	$V_{RM}=V_{RRM}$ $T_j=25^\circ\text{C}$	—	—	50	μA
ピーク順電圧 Peak Forward Voltage	V_{FM}	$I_{FM}=0.5\text{A}$ $T_j=25^\circ\text{C}$	—	—	0.80	V
熱抵抗 Thermal Resistance	接合部・周囲間 (Junction to Ambient)	Glass-Epoxy Substrate mounted *	—	—	300	$^\circ\text{C/W}$
	接合部・リード間 (Junction to Ambient)		—	—	70	$^\circ\text{C/W}$

* Soldering Leads = 1×1 mm, Both Sides

■定格・特性曲線

FIG.1

順電圧特性
FORWARD CURRENT VS. VOLTAGE

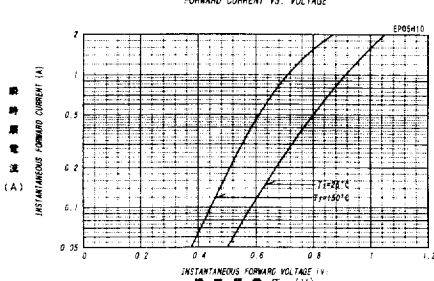


FIG.4

平均逆電力損失
AVERAGE REVERSE POWER DISSIPATION

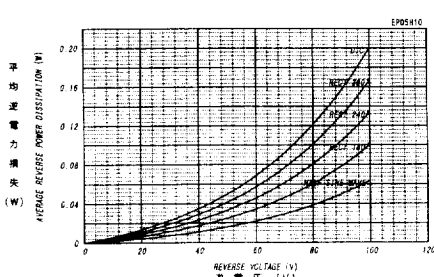


FIG.7

サージ順電流定格
SURGE CURRENT RATINGS

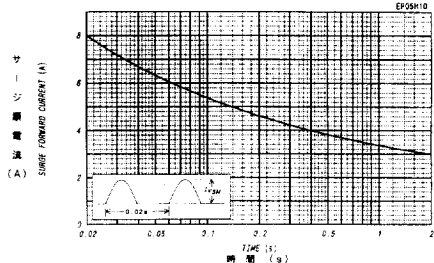


FIG.2

平均順電力損失特性
AVERAGE FORWARD POWER DISSIPATION

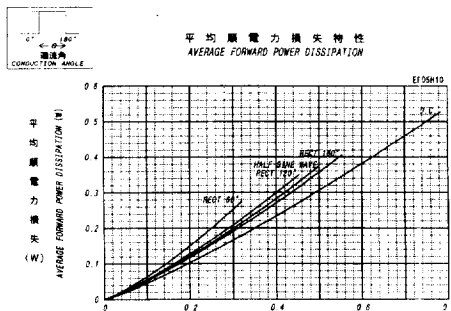


FIG.5

平均順電流 - 周囲温度定格
AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

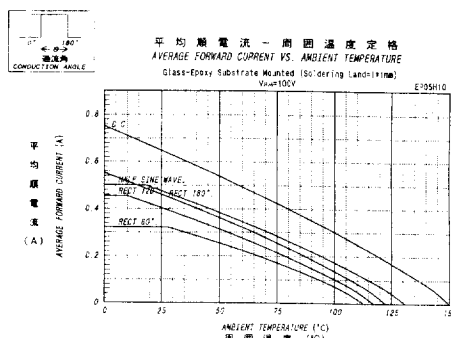


FIG.8

接合容量特性
JUNCTION CAPACITANCE VS. REVERSE VOLTAGE

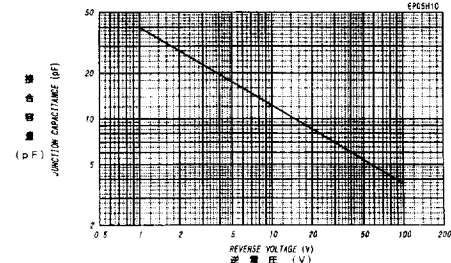


FIG.3

ピーク逆電流 - ピーク逆電圧特性
PEAK REVERSE CURRENT VS. PEAK REVERSE VOLTAGE

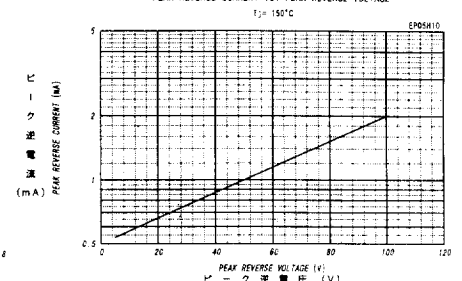


FIG.6

平均順電流 - リード温度定格
AVERAGE FORWARD CURRENT VS. LEAD TEMPERATURE

